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# DoveBid<sup>®</sup> Liquidation

By order of



## **Surplus To Ongoing Operations** ***Semiconductor Fabrication Equipment***

**January 1 - March 31, 2003**

**Dresden, Germany and  
Richmond, VA, USA**

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## Liquidation Begins

January 1, 2003

## Liquidation Ends

March 31, 2003

## Preview Locations

Assets located in Dresden, Germany and Richmond, VA, USA.

## Preview

By appointment only.

For more information or to schedule a preview appointment, please contact:

Guido Boehnke (Germany)

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Phone +49-6047-98-71088

or

Jeff Ritchie (USA)

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Phone +1-650-377-2672

## Additional Information

- A buyer's premium will apply at this sale

## DOVEBID<sup>®</sup> LIQUIDATION

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Participating in a (Liquidation / Private Treaty) is easy. Simply inspect the assets for sale, select the items you wish to purchase, and then either email us your bid using our online Bid Submission Form or discuss pricing with our agent. Sometimes an "ask-and-take" price is established for each item; other times we will invite you to make your best offer. Our agent is always happy to review any bid submitted and will notify you promptly whether the offer has been accepted. We invite you to submit your offer today!

Here's how to participate:

- Review the assets on-location or online at [www.dovebid.com](http://www.dovebid.com)
- All bids must be full conformance with the Terms and Conditions on the Bid Submission Form – and bids that are not submitted in full conformance will be disqualified.
- Payment – Full payment in certified funds will be required.

Further information – For information regarding the liquidation/private treaty process or procedures, please contact:

Guido Boehnke (Germany)

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Jeff Ritchie (USA)

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## Auctioneer's Note

DoveBid is extremely pleased to have been selected by Infineon Technologies Villach to conduct a Private Treaty Liquidation sale of assets surplus to its ongoing production. The sale features high-end Semiconductor Fabrication equipment, including:

- Photo Lithography
- Etch
- Wet Bench
- And more!

The equipment is available by negotiated sale immediately through March 31, 2003. Interested buyers must contact the listed person to arrange for equipment inspection and bid submission. Feel free to attend the preview or visit our website at [www.dovebid.com](http://www.dovebid.com) to download the equipment catalog with a complete asset listing.

Please remember all assets are sold as is, where is, and with all faults when participating in an auction. Buyers are responsible for removal of assets and all shipping and rigging charges.

On behalf of Infineon, we welcome your participation in this exciting, world-class liquidation event.

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# Infineon Liquidation



Nikon Scanner S103B/300



Canon FPA-3000EX4

## PHOTO LITHOGRAPHY

### Dresden, Germany

1 - **NIKON - SCANNER S103B/300**, Tool ID FOT317-01, S/N 7912005, May 2000, Current Software Revision SW J3.32S GEM Compliant Software, 12-Inch (8-Inch Possible After Rebuild) Wafer Size, 6-Inch & 0.25-Inch Reticle Size, 4:1 Lens-Reduction Ratio, 25x33 mm Field Size, 365nm Exposure Wavelength, I-Line Lamp USHIO 2kW Power Light Source, 0.35 or Better Resolution, 40nm for FIA System Alignment Accuracy, 50 wph (12" / 120 shots / 40 mJ / cm<sup>2</sup>) Throughput, (W x D x H) 2500mm x 2600mm x 3350mm; Product Features: Off-Axis Illumination Mode, Variable Numeric Aperture (NA) from 0.45 to 0.60, Off-Axis FIA, LSA Alignment System, Multi Window Operation and Analysis Software, EMO Guard Ring; Configuration Features: Reticle Bar Code Reader for N type, Special Type Wafer Auto Feeder (12"), Left In-Line Unit, Pellicle Particle Checker, Reticle Bar Code Reader, Process Unit/ Temperature Control Unit/ Operation Control Unit Not Separately; All Units Located in One Plane

### Dresden, Germany

1 - **CANON EX3L**, Tool ID FOT301-01, S/N 710147, Cymer Laser S/N 3093, 2.37 Billion Pulses Shots on Laser, Current Software Revision 10.04b, 12-Inch Wafer Size, 6-Inch & 0.25-Inch Reticle Size, 5:1 Lens Reduction Ratio, 22mm x 22mm Field Size, 248nm Exposure Wavelength, 1-kHz KrF Excimer Laser (ELS-4300) Light Source, 0.25um Resolution, Spec: 80nm Alignment Accuracy, (Spec: 20) 31 wph (12-inch, 120 shots, 0.17s timer expos) Throughput, (W x D x H) 1900mm x 2850 (with laser 4350) mm x 2450mm; Product Features: Fast Linear Motor Air Guided Tilting (FLAT) Stage for Higher Throughput and Alignment Accuracy, CQUEST II Off-Axis Illumination Mode, CCD-OPTF II System, Variable Numeric Aperture (NA) from 0.40 to 0.60, FRA System, HeNe Off-Axis AGA System, Multi Window Operation Software, Canon Standard On-Line Software, Chuck Maintenance Unit (special 12"), EMO Guard Ring; Configuration Features: Reticle Bar Code Reader For N Type, Special Wafer Auto Feeder and Low Contact TiO2 Wafer Chuck, Left In-Line Unit, Standard Type Laser Delivery Optics (Same Floor), Pellicle Particle Checker, Special Chemical Filter - System includes a Standard Chemical Filter to reduce Ammonia and NMP Concentrations, all Utilities are Bottom Feed including Exhaust

### Dresden, Germany

1 - **TEL ACT12**, Tool ID FOT305-01, S/N MD-E170006, 1997, Current Software Revision 1.8, Configuration Features: 12-Inch (No 8-Inch Conversion Possible), Coat Unit: 1 Unit with (4) Resist Dispense Lines, Side Rinse (EBR) Arm, TEL RRC Option, Wind Velocity Sensor, Central Supply for Solvent, Canister Supply possible (Prepared), Direct Resist Drain Connection, TARC Unit: 1 Unit with (2) Resist Dispense Lines, Side Rinse (EBR) Arm, TEL RRC Option, Wind Velocity Sensor, Central Supply for Solvent, Canister Supply Possible (Prepared), Direct Resist Drain Connection, Developer: 2 Units with One Developer Dispense Line with Canister Supply, One Unit with H-Nozzle, One Unit with E2-Nozzle, DI-

Water Rinse Line, Direct Developer Drain Connection, WEE: 1 Unit 248nm, 2 Unit High Hot Plate (HHP), 3 Units CPL, 6 Units LHP, (W x L x H) 1800mm x 750mm x 1850mm, Standard BARC/DUV Process: 40 wph Throughput, 3 FOUF Ports; Special Features: Interface for Nikon Exposure Tools, Main Controller (M/C) Version 1, T/H Controller for Spinner Units (Coat & Develop), Software Options, Advanced Cascade Wafer Flow Software, Parallel Wafer Flow Software, Process Log Software

### Richmond, Virginia, USA

1 - **CANON FPA-3000EX4**, Tool ID DUVS02LA, S/N 8034056, Cymer Laser S/N 3146, 8.3 Billion Pulses Shot on Laser, Current Software Revision 11.08a, 8-Inch Wafer, 6-Inch & 0.25-Inch Reticle Size, 5:1 Lens Reduction Ratio, 22mm x 22mm Field Size, 248nm Exposure Wavelength, 1-kHz KrF Excimer Laser (ELS-5300) Light Source, 0.25um Resolution, 50nm Alignment Accuracy, 73 wph (8-inch, 60 shots, 300J/m<sup>2</sup>) Throughput, (W x D x H) 1900mm x 2600mm x 2450mm, Product Features: Fast Linear Motor Air Guided Tilting (FLAT) Stage, CQUEST II Off-Axis Illumination Mode, CCD-OPTF II System, Variable Numeric Aperture (NA) from 0.40 to 0.60, FRA System, HeNe Off-Axis AGA System, Multi Window Operation Software, Canon Standard On-Line Software, Chuck Maintenance Unit, EMO Guard Ring; Configuration Features: Reticle Bar Code Reader for N type, Type VI Wafer Auto Feeder and Low Contact TiO2 Ring Wafer Chuck, Left In-Line Unit, Standard Type Laser Delivery Optics, Pellicle Particle Checker, Reticle Cassette Bar Code Reader, Special Chemical Filter (System Includes a Standard Chemical Filter to Reduce Ammonia and NMP Concentrations), All Utilities are Bottom Feed including Exhaust, Exhaust is Routed within Tool Footprint

### Richmond, Virginia, USA

1 - **CANON FPA-3000EX4**, Tool ID DUVS06LB, S/N 8054071, Laser S/N 3116, 8.8 Billion Pulses Shots on Laser, Current Software Revision 11.08a.06, 8-Inch Wafer, 6-Inch & 0.25-Inch Reticle Size, 5:1 Lens Reduction Ratio, 22mm x 22mm Field Size, 248nm Exposure Wavelength, 1-kHz KrF Excimer Laser (ELS-5300) Light Source, 0.25um Resolution, 50nm Alignment Accuracy, 73 wph (8-inch, 60 shots, 300J/m<sup>2</sup>) Throughput, (W x D x H) 1900mm x 2600mm x 2450mm, Product Features: Fast Linear Motor Air Guided Tilting (FLAT) Stage, CQUEST II Off-Axis Illumination Mode, CCD-OPTF II System, Variable Numeric Aperture (NA) from 0.40 to 0.60, FRA System, HeNe Off-Axis AGA System, Multi Window Operation Software, Canon Standard On-Line Software, Chuck Maintenance Unit, EMO Guard Ring; Configuration Features: Reticle Bar Code Reader for N type, Type VI Wafer Auto Feeder and Low Contact TiO2 Ring Wafer Chuck, Left In-Line Unit, Standard Type Laser Delivery Optics, Pellicle Particle Checker, Reticle Cassette Bar Code Reader, Special Chemical Filter (System Includes a Standard Chemical Filter to Reduce Ammonia and NMP Concentrations), All Utilities are Bottom Feed including Exhaust - Routed within Tool Footprint

### Richmond, Virginia, USA

1 - **CANON FPA-3000EX4**, Tool ID DUVS07LB, S/N 8044060, Cymer Laser S/N 3168, 9.0 Billion Pulses Shots on Laser, Current Software Revision 11.07d.02, 8-Inch Wafer, 6-Inch & 0.25-Inch Reticle Size, 5:1 Lens Reduction Ratio, 22mm x 22mm Field Size, 248nm Exposure Wavelength, 1-kHz KrF Excimer Laser (ELS-5300) Light Source, 0.25um Resolution, 50nm Alignment Accuracy, 73 wph (8-inch, 60 shots, 300J/m<sup>2</sup>) Throughput, (W x D x H) 1900mm x 2600mm x 2450mm, Product Features: Fast Linear Motor Air Guided Tilting (FLAT) Stage, CQUEST II Off-Axis Illumination Mode, CCD-OPTF II System, Variable Numeric Aperture (NA) from 0.40 to 0.60, FRA System, HeNe Off-Axis AGA System, Multi Window Operation Software, Canon Standard On-Line Software, Chuck Maintenance Unit, EMO Guard Ring; Configuration Features: Reticle Bar Code Reader for N type, Type VI Wafer Auto Feeder and Low Contact TiO2 Ring Wafer Chuck, Left In-Line Unit, Standard Type Laser Delivery Optics, Pellicle Particle Checker, Reticle Cassette Bar Code Reader, Special Chemical Filter (System includes a Standard Chemical Filter to Reduce Ammonia and NMP Concentrations), All Utilities are Bottom Feed including Exhaust, Exhaust is routed within Tool Footprint

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# Infineon Liquidation



TEL Clean Track Mark-8

## **Richmond, Virginia, USA**

**1 - CANON FPA-3000EX4**, Tool ID DUVS01LA, S/N 7104013, Cymer Laser S/N 086, 7.7 Billion Pulses Shots on Laser, Current Software Revision 11.08a, 8-Inch Wafer, 6-Inch & 0.25-Inch Reticle Size, 5:1 Lens Reduction Ratio, 22mm x 22mm Field Size, 248nm Exposure Wavelength, (1) kHz KrF Excimer Laser (ELS-5300) Light Source, 0.25um Resolution, 50nm Alignment Accuracy, 73 wph (8-inch, 60 shots, 300J/m<sup>2</sup>) Throughput, (W x D x H) 1900mm x 2600mm x 2450mm, Product Features: Fast Linear Motor Air Guided Tilting (FLAT) Stage, CQUEST II Off-Axis Illumination Mode, CCD-OPTF II System, Variable Numeric Aperture (NA) from 0.40 to 0.60, FRA System, HeNe Off-Axis AGA System, Multi Window Operation Software, Canon Standard On-Line Software, Chuck Maintenance Unit, EMO Guard Ring; Configuration Features: Reticle Bar Code Reader for N type, Type VI Wafer Auto Feeder and Low Contact TiO<sub>2</sub> Ring Wafer Chuck, Left In-Line Unit, Standard Type Laser Delivery Optics, Pellicle Particle Checker, Reticle Cassette Bar Code Reader, Special Chemical Filter (System Includes a Standard Chemical Filter to Reduce Ammonia and NMP Concentrations), All Utilities are Bottom Feed including Exhaust, Exhaust is Routed within Tool Footprint

## **Dresden, Germany**

**1 - CANON-STEPPER FPA-3000 EX3**, Tool ID FOT007-02, S/N 612123, 1996, Current Software Revision V 8.10A Online97 Compliant Software, 8-Inch (6-Inch possible after rebuild) Wafer Size, 6-Inch & 0.25-Inch Reticle Size, 5:1 Lens Reduction Ratio, 22x26 mm Field Size, 248nm Exposure Wavelength, Cymer Laser 4300 Series Bandwidth: 1.2pm; Power: 7.2W; Rep Rate: 600Hz with 12mJ each Puls Light Source, 0.25 or better Resolution, 65nm for HeNe Alignment Accuracy, 54 wph (8" / 78 shots / 20 J / m<sup>2</sup>) Throughput, (W x D x H) 1900mm x 2600mm x 2450mm, Product Features: Off-Axis Illumination Mode, Variable Numeric Aperture (NA) from 0.40 to 0.60, HeNe TV AGA, Broadband AGA and TTL Off-Axis Alignment System, Multi Window Operation And Analysis Software, EMO Guard Ring; Configuration Features: Reticle Library for Nikon Type, Reticle Bar Code Reader for Nikon Type, Pellicle Particle Checker, Left In-Line Unit, Process Unit/ Temperature Control Unit/ Operation Control Unit Not Separately; all units located In One Plane

## **Dresden, Germany**

**1 - TEL CLEAN TRACK MARK-8**, Tool ID FOT008-02, S/N MD 826845, 1996, Current Software Revision V 2.35 Host Comm. GEM1.72 Software, 8-Inch (6-Inch Possible After Rebuild) Wafer Size, 40 Wafer per Hour Throughput, Main Machine: 4290mm x 1360mm x 2270mm, Chemical Cabinet 1: 600mm x 650mm x 1500mm, Chemical Cabinet 2: 1730mm x 650mm x 1500mm, HMDS Cabinet: 500mm x 450mm x 800mm, Temperature Control Rack: 900mm x 650mm x 1500mm, Temp & Humidity Controller: 1121mm x 600mm x 950mm, Configuration Features: Block 1: Carrier Station, 4 I/O Ports, Cup Wash Holder; Block 2: B.ARC Coater (Each Coater Unit is Equipped with Millipore GENII Pump, Programmable EBR Nozzle, RRC Nozzle and Air Condition by Shinwa Temperature & Humidity Controller) - (2) Resist Lines, POSI Coater - (3) Resist Lines, (2) Adhesion Unit, (4) Low Oven, (2) Cool Plate, (2) Dehydration Hot Plate; Block 3: (2) Developer Unit with (1) Developer Dispense Line with E\_ Nozzle & Rinse Nozzle & PDD Nozzle, (2) CHP Unit, (2) Low Oven, (2) Cool Plate, (1) WEE Unit; Block 4: Interface for CANON FPA Stepper; Note: Solvent and Developer Solution Provided by 2 Tank Auto Supply Function

## **ETCH**

### **Dresden, Germany**

**1 - AMAT P5000 MxP OXIDE SYSTEMS WITH ESC**, Tool ID ETC002-01, 1995, Current Software Revision B4.80, System Options: 8-Inch Wafer Size, Top Mount (3 Chambers), WPS (Wafer Position Sensor), ESC (Electrostatic Chuck), Voltage 208V/50Hz, Mainframe P5000 Mark II XT Etch, MxP Chambers, Remote Frame Modular, Generator ENI OEM-12b, Neslab Heat Exchanger, AMAT 0 Heat Exchanger

### **Dresden, Germany**

**2 - AMAT P5000 MxP OXIDE SYSTEMS WITH ESC**, Tool ID's ETC004-01 & ETC004-02, 1995, Current Software B4.80, System Options: 8-Inch Wafer Size, Top Mount (3 Chambers), WPS (Wafer Position Sensor), ESC (Electrostatic Chuck); Voltage 208V/50Hz, Mainframe P5000 Mark II XT Etch, (3) MxP Chambers, Remote Frame Modular, (3) Generator ENI OEM-12b, Neslab Heat Exchanger, AMAT 0 Heat Exchanger

# Infineon Liquidation



AMAT P5000 Etch MxP Oxide Systems with ESC



Jeol  
JWC7500E



300MM Wet Bench Stellaris 3.18



## CVD

### Dresden, Germany

1 - **AMAT P5000**, Tool ID ETC014-01, 1995, Current Software Revision b6.02\_8, 8-Inch Wafer Size, Voltage 208V/50Hz, (1) Mainframe P5000, (4) Chambers (2 TEOS Doped, 1 Enh Conv Nitride, 1 Sputter Etch), (1) Remote Frame Modular, (1) Delta Remote Frame, (2) Generator ENI OEM-12b, (1) Minicontroller, (1) Neslab Heat Exchanger, (1) Amat 0 Heat Exchanger

## WET BENCHES

### Dresden, Germany and Richmond, Virginia USA

**SEMITOOL MAGNUMS**, Tool ID'S NAS009-01 & NAS009-02, 1996, NAS009-01 Product Features: Batch, Fully-Automated 25-Wafer, Double Chamber Chemical Stripping, Double Chamber Cleaning Spray Solvent Tool, Chamber Material for Etch/Strip: HF-Resistant Teflon Bowl, Chamber Material for Solvent Application: Stainless Steel Bowl, (1) Spin Rinser Dryer for all 4 Process Chamber, (1) End Effector/Robot Dryer/Cleaner, Wafers Rotate within a Cassette, On-Axis Orientation, Programming Versatility, Gases Like Ozone or CO2 can be Connected, (1) Chemical Mixing Tank for Chemistry A and B (One Use/No Refill) and (1) Chemical Tank for A or B (Recirculation/Refill) per Spray Acid Chamber (Total 4 Tanks a 15 l), (1) Chemical Fresh Tank, (1) Chemical Recirculation Tank per Spray Solvent Chamber for Solvent X and (1) Chemical "Recirculation" Tank per Spray Solvent Chamber for Solvent Y, Only (1) Chemical "Fresh" Tank Y (Total 7 Tanks a 15 l), Both Process Applications can run Parallel, Throughput Depends on Drying Module, Loading Station for 4 Lots (Pre-Load 2 Lots per Process or 1 Lot per Chamber), NAS009-02 Product Features: Batch, Fully-Automated 25-Wafer, Double Chamber Chemical Stripping Tool, Chamber Material For Etch/Strip: HF-Resistant Teflon Bowl, (2) Spin Rinser Dryer (Dryer Per Chamber), (1) End Effector/Robot Dryer/Cleaner, Wafers Rotate Within A Cassette, On-Axis Orientation, Programming Versatility, Gases Like Ozone or CO2 Can Be Connected, (1) Chemical Mixing Tank for Chemistry A and B (One Use/No Refill) and (1) Chemical Tank for A or B (Recirculation/Refill) per Spray Acid Chamber (Total 4 Tanks A 15 L), Loading Station For 4 Lots

### Dresden, Germany

1 - **300MM WET BENCH STELLARIS 3.18**, Tool ID NAS 307-01, 1998, Current Software Revision 2.0, 12-Inch Wafer, PRI-Buffer Station, Berkeley Handlings Station, Process Modules, Max. 250 wph Process Dependent, 761.5cm x 226.1cm x 250.0cm, Product Features: FOUP Buffering, Twelve-FOUP Buffer, Supports Overhead Delivery, Batch Wafer Transfer, OCR Option (First Wafer Only), Notch Alignment Option, Face-to-Face Processing, Single Wafer Transfer, Supports Partial FOUP Processing, Input/Output Module uses Dual SCARA Robots with proven reliability, Process Flexibility, System 4000 Software, Reduced Cassette, Reduced DI Water Usage, Filtered, Recirculated Process Module, OFR Rinse Tank, IPA Dryer Technologies (Yield Up)

## METRO

### Dresden, Germany

1 - **JEOL JWC7500E SEM INSPECTION TOOL**, S/N WS175022 - 52, 1820(W) x 1270(D) x 1505(H), Weight: Main: 1000kg, Operation Console:175kg, Pump Console:180kg; only for 8" Wafer; Acceleration Voltage until 6000V; Stage with X,Y,R (0 to 360°), T (-30 to +60°); Host-Communication via RS232; without EDX; without Roughness Pump

## MISCELLANEOUS

### Munich, Germany

1 - **5200 LPCVD CENTURA FOR 150MM WAFERS**, LPCVD Centura Mainframe, Chamber A: LPCVD Nitride and Oxide Chamber, Gaspanel Configuration NF3, SiH4, N2O, NH3, N2 and H2; Chamber B: Empty; Chamber C: Empty; Chamber D: Empty; Chamber F:Cooldown Chamber

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